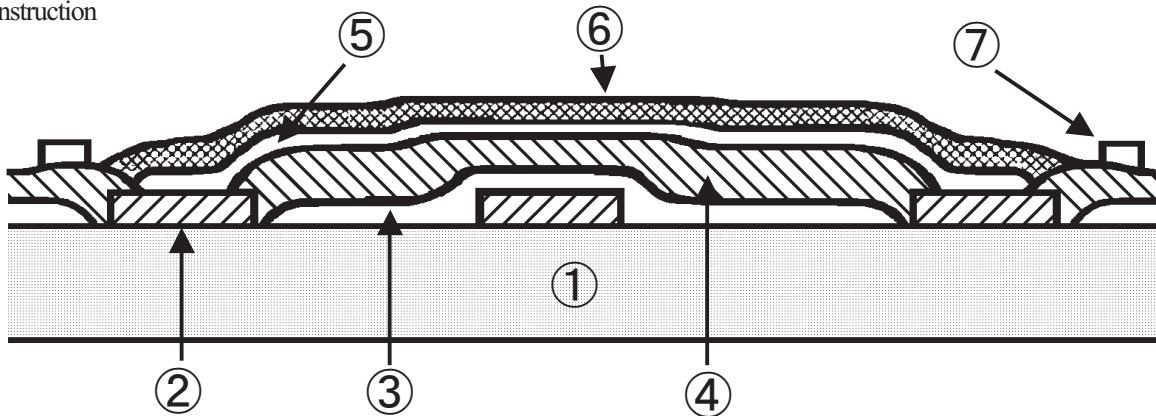


## ■ Features

- High density and miniaturized design is achieved through using double layered conductive paste jumpers .
- Easy to design long cross jumpers.
- Cross-over jumpers allow greater cost reduction than wire jumpers.
- Free design capability.
- Copper paste jumpers for migration free wiring.
- Shield effect pattern design capability.

## ■ Construction



| No. | Name            | No. | Name         |
|-----|-----------------|-----|--------------|
| ①   | Base            | ⑤   | Paste Jumper |
| ②   | Copper Foil     | ⑥   | Overcoat     |
| ③   | Solder Resist   | ⑦   | Marking      |
| ④   | Insulated Layer |     |              |

## ■ Specification

| Item                   | Specification    | Condition             |
|------------------------|------------------|-----------------------|
| Paste Jumper Line      | Conductive Resin | Silver, Copper        |
| Ambient Temperature    | -30°C ~ +100°C   |                       |
| Range of Resistance    | Ag               | 120mΩ/□               |
|                        | Cu               | 60mΩ/□                |
| Rated Current          | 100mA/1mm Width  |                       |
| Max. Operation Voltage | Ag               | 20V                   |
|                        | Cu               | 50V                   |
| Breaking Voltage       | DC100V 1min.     |                       |
| Insulation Resistance  | >100MΩ           | DC50V 1min.           |
| Solder Dipping         | 200mΩ/□          | 260°C 5sec.           |
| Load Life              | 200mΩ/□          | 70°C 500Hr            |
| Humidity Load Life     | 200mΩ/□          | 40°C 90 ~ 95%RH 500Hr |
| High Temperature       | 200mΩ/□          | 100°C 500Hr           |
| Humidity               | 200mΩ/□          | 40°C 90 ~ 95%RH 500Hr |